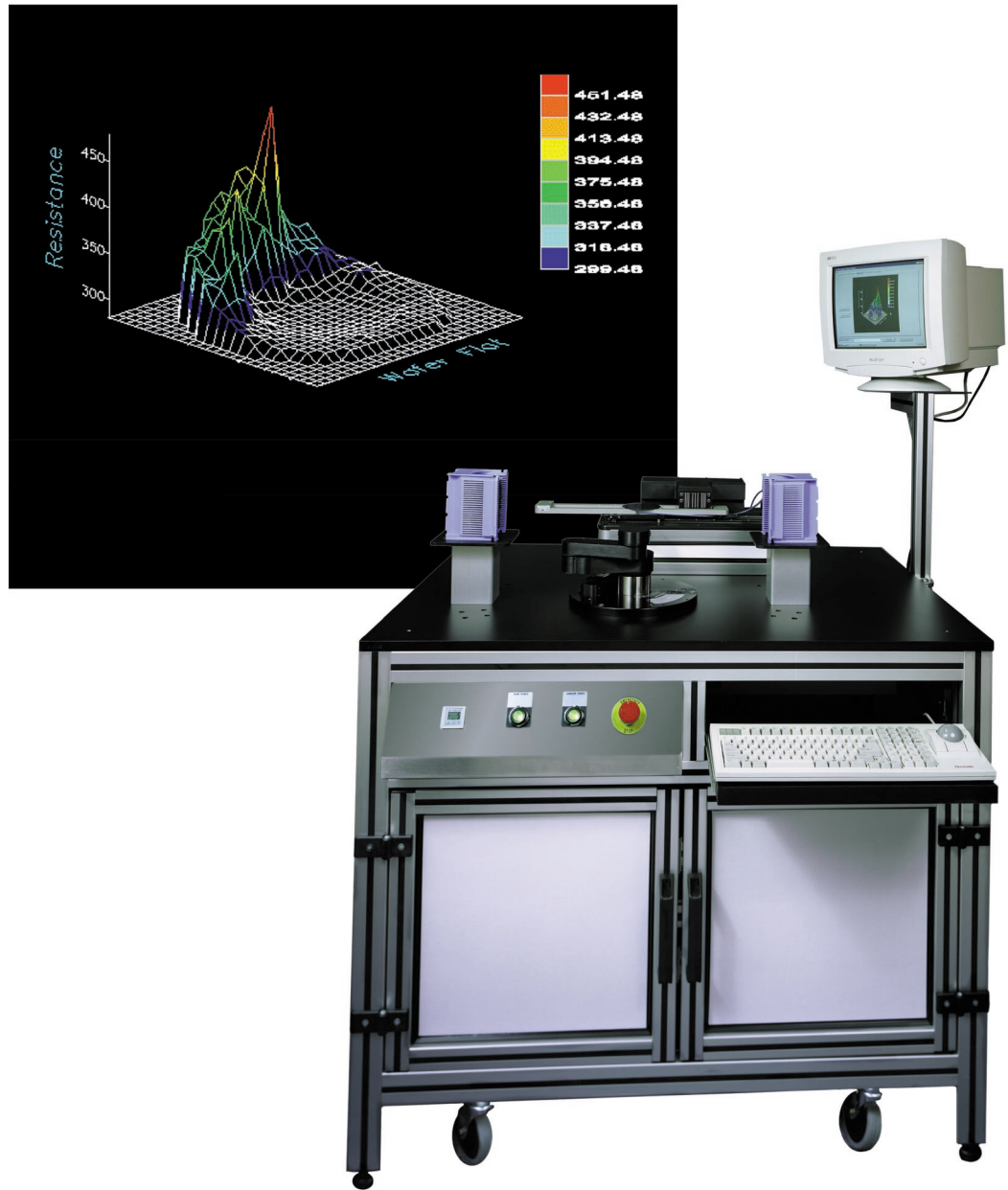




Contactless Bulk Resistivity / Sheet Resistance Measurement and Mapping Systems

1500 Family



LEI 1510RS (Robotic Sorting) shown with 2 cassettes (product may differ from photo)

***Process Monitoring & Quality Control
for High Production Yields.***

Specifications



Characterization of

- **GaAs wafers** (epi, annealed ion-implants on semi-insulating and some doped* substrates)
- **Silicon wafers** (bulk Si, epi, annealed ion-implants, and POCl₃ doping uniformity on high resistivity substrates)
- **Thin film metallizations**

* Contact factory for details.

Performance

(Conforms to ASTM F673)

- Based on the average of three 150 center-point tests (contact LEI for complete details). Where available, the data below is derived using NIST-traceable, uniformly-doped silicon standards. These tests are conducted with samples manually placed on handler rails and a ≥ 0.035 " gap setting. NIST and VLSI standard wafers are available for calibration.

	Sheet Resistance*	Standard Deviation*	Bulk Resistivity*
HI	3000 ohm/□	1.00%	200 ohm-cm
	600 ohm/□	0.20%	30 ohm-cm
	15 ohm/□	0.10%	1 ohm-cm
LO	15 ohm/□	1.00%	1 ohm-cm
	2 ohm/□	0.20%	0.1 ohm-cm
	0.2 ohm/□	0.25%	0.01 ohm-cm
XL	1.5 ohm/□	0.70%	0.1 ohm-cm
	0.2 ohm/□	0.55%	0.01 ohm-cm
	0.1 ohm/□	0.55%	0.005 ohm-cm

* Based on keyboard entry of known thickness

* Sheet Resistance values \neq Bulk Resistivity values

Linearity

- .035 to 3,000 Ohms/□ $< \pm 3\%$

Thin-film thickness

- Thickness = $\frac{\text{Bulk resistivity (known)}}{\text{Sheet resistance (measured)}}$

Measurement Capabilities

- Nominal sample thickness range of 450 to 800 microns
- Normal ≥ 0.035 " (.889mm) gapping preset at factory
- Factory-adjustable gap to accommodate thicker substrates
- Robotic measurement of 2", 3", 4" (100mm), 6" (150mm), and 8" (200mm) wafers (optional)

Wafer Thickness

- Capable of calculating resistivity with keyboard-entered thickness
- Optional capacitance thickness probes

Sensor Transducer Sizes

- **HI Range** 14 mm diameter
- **LO Range** 14 mm diameter
- **XL Range** 14 mm diameter

Sample Handling and Sensing

- Up to 300 measurement points
- Automatic drift compensation
- Software-selectable resistivity ranges

Operating Characteristics

- High spatial resolution
- Precise voltage regulation for tight linearity and consistently repeatable results

Calibration

- Performed via easy-entry computer screen
- Software-controlled (no manual adjustments)
- 16 bit system for data acquisition

Computerization

- System is network- and Windows XP compatible
- Setup information may be saved under operator-designated file names
- Ability to create custom test point plans
- Measurements and associated test plans can be graphically displayed
- Computer, FPD and printer included
- Ethernet network connection

" We estimate we save a minimum of \$250K per year by having the Leighton systems."*

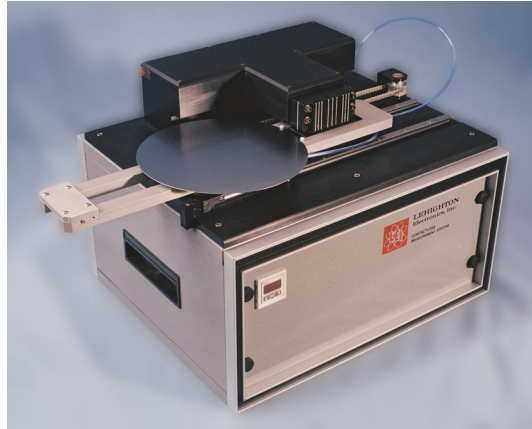
-Dr. Martin J. Brophy
Senior Process Engineer for Wafers/Implant/Anneal
TriQuint Semiconductor

* Please visit us on the web at www.leighton.com/fabtech1/index.html to view this and other testimonials.

Models/Options



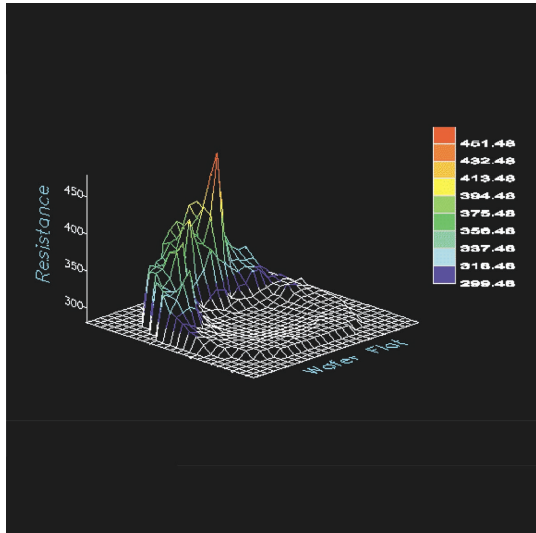
LEI 1510RP The unit shown accommodates 2" to 200mm (8") wafers (max. diameter).



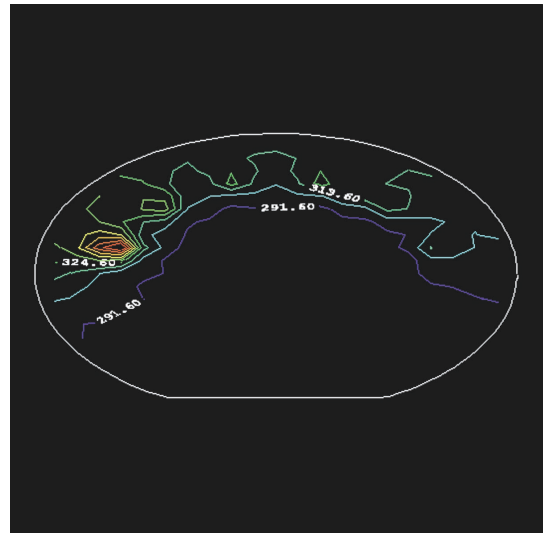
1510 standalone

	1510B			1510C		
	manual	RP	RS	manual	RP	RS
throughput (wafer test time)						
<i>single wafer</i>						
9 point plan	0:45	0:45	0:45	0:22	0:22	0:22
24 point plan	2:45	2:45	2:45	1:15	1:15	1:15
55 point plan	5:30	5:30	5:30	2:30	2:30	2:30
<i>25 wafer cassette*</i>						
10 center plan	N/A	27:00	27:00	N/A	13:50	13:50
24 point plan	N/A	42:15	42:15	N/A	21:15	21:15
55 point plan	N/A	80:00	80:00	N/A	41:00	41:00
robotic handling of sample wafers						
<i>single cassette</i>	NO	YES	YES	NO	YES	YES
<i>multiple cassette</i>	NO	NO	YES	NO	NO	NO
repeatability						
<i>positional</i>	±.003" (.0762mm)			±.0015" (.0381mm)		
<i>rotational</i>	±2.5°			±1°		

* Ideal throughput does not include time to change cassette.
Throughput times are calculated with the Auto Reference feature on.
RP(Robotic Pick-and-Place), RS(Robotic Sort)



surface map



contour map

Accessories and Options

- Cassette-to-cassette sorting
- Capacitance thickness capability
- Wafer mapping
- SPC
- 1-4 cassettes for 2", 3", 4" (100mm), 6" (150mm) wafers
- 2 cassettes for 8" (200mm) wafers
- Scanning End Effector
- Light Shield

Available Power Configurations

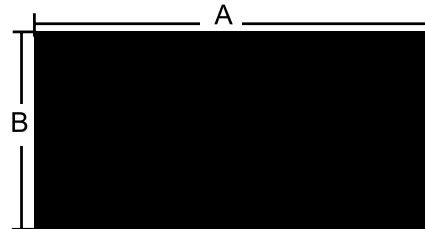
- 117 VAC \pm 10% 50-60 Hz
- 220 VAC \pm 10% 50-60 Hz
- 100 VAC \pm 10% 50-60 Hz

Vacuum

- 40-60 cm Hg

1510RP/RS Footprint

Manual	A (width)	B (depth)
Tabletop Stand Alone	32.5" (825.5mm)	14.5" (368.3 mm)
Robotic	A (width)	B (depth)
1510RP	39" (990.6mm)	41" (1040mm)
1510RS	48" (1219mm)	40" (1014mm)



* Specifications subject to change; contact LEI for the latest details.

For More Information:

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 (610) 377-6820

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300mm Resistivity Thickness has arrived!

LEI RS300 (200-300mm with integrated thickness)
 footprint: 86" (2184mm)w x 40" (1016mm)d w/monitor float

Contact LEI for more details.